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TP8-GC002

Product technical specifications

Thermal Conductive Material Series-Thermal Pad

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Product Description

TP8-GC002 has good insulation, pressure resistance, flexibility and excellent thermal conductivity. The surface has natural tack, which can fill the gap and squeeze out the air between the heat source and the radiator to achieve full contact and effectively improve the heat transfer efficiency. It can meet the design requirements of miniaturization and ultra-thin equipment. It is an excellent thermally conductive filler material and is widely used in various electronic components.

Typical Applications

- Between heat-generating semiconductors and a heat sink
- Between heat-generating magnetic components and a heat sink
- Area where heat needs to be transferred to a frame, chassis, or other type of heat spreader
- Telecommunications, Computer and peripherals, Power conversion, Consumer electronics

Features and Benefits

Low thermal impedance

Electrically isolating

Comfortable gap filling material

Natural tack for easy assembly

Thermal conductivity : 8.0 W/mK

Designed for low-stress applications

Enhanced puncture, shear and tear resistance

Product Performance

PROPERTIES	UNIT	TEST EQUIPMENT	VALUE	TEST METHOD
Color	/	/	Gray	Visual
Thickness	mm	PEACOCK thickness gauge	0.5~6.0	ASTM D374
Density	g/cc	ZMD series electronic density meter	3.3±0.2	ASTM D792
Hardness	Shore C	LX-C type hardness tester	30~45	ASTM D2240
Temperature Range	°C	Programmable hot and cold impact box	- 40~180	/
Dielectric Breakdown Voltage	KV/mm	RK2674A Withstand pressure tester	> 9	ASTM D149
Volume Resistivity	Ω.cm	Rk2683 A Insulation resistance tester	≥ 10 ¹²	ASTM D257
Flame Rating	/	Flame retardant tester	V-0	UL 94
Thermal Conductivity	W/mK	DRL - V interface material thermal resistance tester	8.0	ASTM D5470
Silicone permeability	%	High temperature oven, Electronic balance	≤3	125°C/72h (compression 50%)